

Amendments to the Specification

Please replace paragraph [0014] beginning on page 6, line 1 with the following amended paragraph:

A1 Preferably, the second region comprises a plurality of projecting parts each of which extends vertically from the first region, and the projecting ~~[[pats]]~~ parts of the second region are extended from both sides of the first region. Further, the connecting portion may be shaped to decrease in area gradually from the conductive post to the conductive wiring pattern. At least one of the projecting ~~[[pats]]~~ parts may form a part of the conductive post.

Please replace paragraph [0017] with the following amended paragraph:

A2 For better understanding of the present invention, a conventional technology is first described in conjunction with Figs. 1 to 4. Fig. 1 is a cross-sectional view showing a conventional chip-size semiconductor package 10. Fig. 2 is a plan view showing the conventional chip-size semiconductor package 10, shown in Fig. 1. The chip-size semiconductor package 10 includes a Si chip 12; metal pads 14 formed on the Si chip 12; a wafer coating 16 formed over the Si chip 12; conductive wiring patterns 18 formed on the wafer coating 16; a molding resin 24 formed over the wafer coating 16; conductive posts 20 formed in the molding resin 24; and terminals 22 formed on the molding resin 24. The conductive wiring patterns ~~[[12]]~~ 18 are electrically connected to the metal pads 14 through the wafer coating 16. The terminals 22 are connected to the

A2
conductive posts 20 one by one.

Please replace paragraph [0023] with the following amended paragraph:

A3
The slits 250 are arranged to be separated by a predetermined distance from each other. The slits 250 are shaped to be rectangular and arranged to extend radially, as shown in Fig. 5. According to the first preferred embodiment, the slits 250 are provided, so that stress applied to the connecting portion 240 is dispersed, and the molding resin is well in contact or bonded with the conductive post 220 and conductive wiring ~~patter~~ pattern 218. As a result, the connecting portion 240 is not easily broken.

Please replace paragraph [0026] with the following amended paragraph:

A4
According to the second preferred embodiment, the dummy patterns 350 are provided, so that stress applied to the connecting portion 340 is dispersed, and the molding resin is well in contact or bonded with the conductive post 320 and conductive wiring ~~patter~~ pattern 318. As a result, the connecting portion 340 is not easily broken.

Please replace paragraph [0028] with the following amended paragraph:

A5
According to the third embodiment, the dent 450 is formed around the connecting portion 440, so that stress applied to the connecting portion 440 is dispersed, and the molding resin is well in contact or bonded with the conductive post 420 and conductive wiring ~~patter~~ pattern 418. As a result, the connecting portion 440 is

A5
not easily broken.

Please replace paragraph [0029] with the following amended paragraph:

A6
Fig. 9 is an enlarged view showing a part of a chip-size semiconductor package according to a ~~[[fifth]]~~ fourth preferred embodiment of the present invention. According to the fourth preferred embodiment, a conductive wiring pattern 518 is shaped to have a first region 518a extending outwardly from a conductive post 520 and second regions 518b each of which is extending or projecting vertically from the first region 518a. The projecting ~~[[pats]]~~ parts of the second region 518b are extended from both sides of the first region 518a. One horizontal line of the projecting ~~[[pats]]~~ parts 518b forms a part of the conductive post 520.

Please replace paragraph [0031] with the following amended paragraph:

A7
According to the fourth embodiment, the conductive wiring pattern 518 is shaped to have the first region 518a and second regions 518b extending vertically from the first region 518a, so that stress applied to the connecting portion 540 is dispersed, and the molding resin is well in contact or bonded with the conductive post 520 and conductive wiring ~~patter~~ pattern 518. As a result, the connecting portion 540 is not easily broken.
